



## Design of Adhesive Bonded Joints

Guest Editor:

**Dr. Raul D. S. G. Campilho**

Departamento de Engenharia  
Mecânica, Instituto Superior de  
Engenharia do Porto, 4200-072  
Porto, Portugal

Deadline for manuscript  
submissions:

**closed (30 June 2023)**

### Message from the Guest Editor

The adhesive bonding technology has shown significant improvements over the past few decades, which enabled its application in many industries, such as aerospace, aeronautical and automotive. Experimentally, new adhesives, material combinations, and joint geometries are continuously being explored, leading to innovative designs and improved solutions. On the other hand, analytical and numerical strength prediction models aim to accurately predict the joint's behavior and, as a result, reduce the costs and expedite design. Constant evolution of these models is currently taking place, triggered by the need to model complex materials and loadings, with emphasis to numerical models, including improved fracture modelling by techniques, such as fracture mechanics, cohesive zone models, and the adaptation of recent techniques (including meshless methods). Fatigue and impact loadings are particularly challenging and have recently seen major advances. This Special Issue intends to bring together a significant number of good contributions in this area through high-quality original works in the adhesive joints field.





an Open Access Journal by MDPI

## Editor-in-Chief

### Prof. Dr. Giancarlo Cravotto

Department of Drug Science and  
Technology, University of Turin,  
Via P. Giuria 9, 10125 Turin, Italy

## Message from the Editor-in-Chief

You are invited to contribute either a research article or a comprehensive review for consideration and publication in *Processes* (ISSN 2227-9717). *Processes* is published in open access format – research articles, reviews, and other content are released on the internet immediately after acceptance. The scientific community and the general public have unlimited, free access to the content. As an open access journal, *Processes* is supported by the authors and their institutes through the payment of article processing charges (APCs) for accepted papers. We would be pleased to welcome you as one of our authors.

## Author Benefits

**Open Access:** free for readers, with article processing charges (APC) paid by authors or their institutions.

**High Visibility:** indexed within Scopus, SCIE (Web of Science), Ei Compendex, Inspec, AGRIS, and other databases.

**Journal Rank:** JCR - Q2 (*Engineering, Chemical*) / CiteScore - Q2 (*Chemical Engineering (miscellaneous)*)

## Contact Us

---

Processes Editorial Office  
MDPI, Grosspeteranlage 5  
4052 Basel, Switzerland

Tel: +41 61 683 77 34  
[www.mdpi.com](http://www.mdpi.com)

[mdpi.com/journal/processes](http://mdpi.com/journal/processes)  
[processes@mdpi.com](mailto:processes@mdpi.com)  
[X@Processes\\_MDPI](https://twitter.com/Processes_MDPI)